

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		
CONVEYING PARTY DATA			
	Name	Execution Date	
	SATOSHI WAKATSUKI	03/28/2016	
	HIROSHI NAKAZAWA	03/29/2016	
	ATSUKO SAKATA	03/28/2016	
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PROPERTY NUMBERS Total: 1			
	Property Type	Number	
	Application Number:	15131704	
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ATTORNEY DOCKET NUMBER:	09814.0301		
NAME OF SUBMITTER:	B.CARSON		
SIGNATURE:	/B.CARSON/		
DATE SIGNED:	04/20/2016		
	This document serves as an Oath/Declaration (37 CFR 1.63).		
Total Attachments: 4			
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ACG097410-USA-B

SOLE/JOINT INVENTION
(U.S. Rights Only)
Attorney Docket No.

ASSIGNMENT AND DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS I/We, the below named inventor(s), (hereinafter referred to as Assignor(s)), of a claimed invention in an application for United States Letters Patent entitled:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

filed herewith or on _____ as United States Application No. _____ (Confirmation No. _____)
attached hereto and/or PCT International Application No. _____; and

WHEREAS, Kabushiki Kaisha Toshiba
a corporation of JAPAN

whose post office address is 1-1, Shibaura 1-chome, Minato-ku, Tokyo, JAPAN

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Director of the United States Patent and Trademark Office to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request that the attorneys having Power of Attorney in this application, insert here in parentheses (Application No. _____, filed _____), the filing date and application number of said application when known.

As a named inventor below, I hereby declare that: (1) This declaration is directed to the above-identified application; (2) the above-identified application was made or authorized to be made by me; (3) my residence and mailing address are as stated below next to my name; and (4) I believe I am an original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statements made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under section 1001 of Title 18 of the United States Code.

As a below named inventor, I have reviewed and understand the contents of the application, including the claims, and am aware of the duty to disclose to the USPTO all information known to me to be material to patentability as defined in 37C.F.R. § 1.56.

15/131,704 filed April 18, 2016

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SOLE/JOINT INVENTION
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Authorization To Permit Access To Application by Participating Offices:

☐ If checked, the undersigned hereby grants the USPTO authority to provide the European Patent Office (EPO), the Japan Patent Office (JPO), the Korean Intellectual Property Office (KIPO), the World Intellectual Property Office (WIPO), and any other intellectual property offices in which a foreign application claiming priority to the above-identified patent application is filed access to the above-identified patent application. See 37 CFR 1.14(e) and (h). This box should not be checked if the Applicant does not wish the EPO, JPO, KIPO, WIPO, or other intellectual property office in which a foreign application claiming priority to the above-identified application is filed to have access to the above-identified patent application.

In accordance with 37 CFR 1.14(h)(3), access will be provided to a copy of the above-identified patent application with respect to: 1) the above-identified patent application-as-filed; 2) any foreign application to which the above-identified patent application claims priority under 35 U.S.C. 119(a)-(d) if a copy of the foreign application that satisfies the certified copy requirement of 37 CFR 1.55 has been filed in the above-identified patent application; and 3) any U.S. application-as-filed from which benefit is sought in the above-identified patent application.

In accordance with 37 CFR 1.14(c), access may be provided to information concerning the date of filing the Authorization to Permit Access to Application by Participating Offices.

1. FULL NAME OF SOLE OR FIRST ASSIGNOR Satoshi WAKATSUKI	ASSIGNOR'S SIGNATURE <i>Satoshi WAKATSUKI</i>	DATE <i>March 28, 2016</i>
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3. FULL NAME OF THIRD ASSIGNOR Atsuko SAKATA	ASSIGNOR'S SIGNATURE <i>Atsuko Sakata</i>	DATE <i>March 28, 2016</i>
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filed herewith or on _____ as United States Application No. _____ (Confirmation No. _____)
attached hereto and/or PCT International Application No. _____; and

WHEREAS, Kabushiki Kaisha Toshiba
a corporation of JAPAN

whose post office address is 1-1, Shibaura 1-chome, Minato-ku, Tokyo, JAPAN

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Director of the United States Patent and Trademark Office to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request that the attorneys having Power of Attorney in this application, insert here in parentheses (Application No. _____, filed _____), the filing date and application number of said application when known.

As a named inventor below, I hereby declare that: (1) This declaration is directed to the above-identified application; (2) the above-identified application was made or authorized to be made by me; (3) my residence and mailing address are as stated below next to my name; and (4) I believe I am an original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statements made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under section 1001 of Title 18 of the United States Code.

As a below named inventor, I have reviewed and understand the contents of the application, including the claims, and am aware of the duty to disclose to the USPTO all information known to me to be material to patentability as defined in 37C.F.R. § 1.56.

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In accordance with 37 CFR 1.14(h)(3), access will be provided to a copy of the above-identified patent application with respect to: 1) the above-identified patent application-as-filed; 2) any foreign application to which the above-identified patent application claims priority under 35 U.S.C. 119(a)-(d) if a copy of the foreign application that satisfies the certified copy requirement of 37 CFR 1.55 has been filed in the above-identified patent application; and 3) any U.S. application-as-filed from which benefit is sought in the above-identified patent application.

In accordance with 37 CFR 1.14(o), access may be provided to information concerning the date of filing the Authorization to Permit Access to Application by Participating Offices.

1. FULL NAME OF SOLE OR FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
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2. FULL NAME OF SECOND ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
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